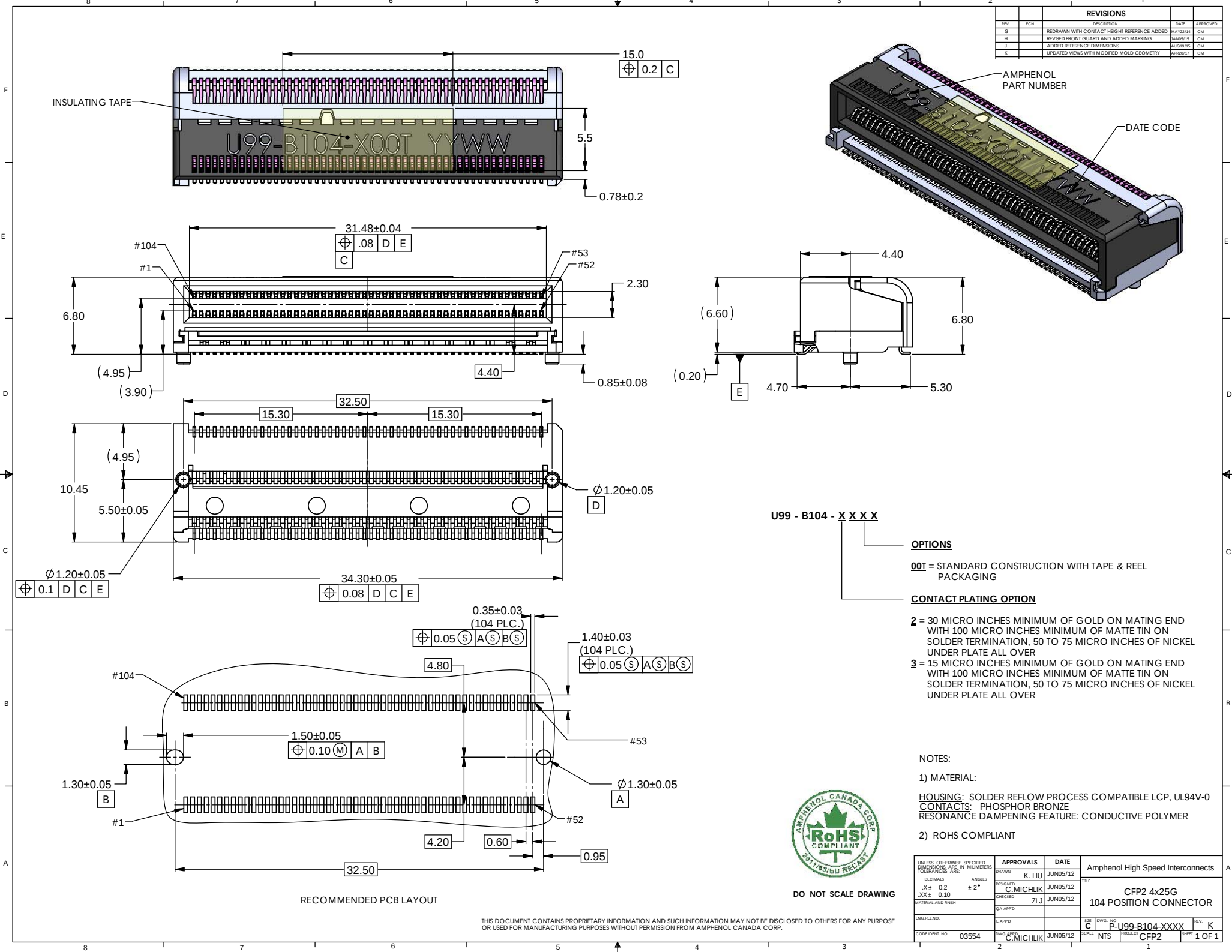




REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
G		REDRAWN WITH CONTACT HEIGHT REFERENCE ADDED	MAY2014	CM
H		REVISED FRONT GUARD AND ADDED MARKING	JAN2015	CM
J		ADDED REFERENCE DIMENSIONS	AUG2015	CM
K		UPDATED VIEWS WITH MODIFIED MOLD GEOMETRY	SEP2017	CM

AMPHENOL
PART NUMBER

DATE CODE

U99 - B104 - X X X X

- OPTIONS**
- 00T** = STANDARD CONSTRUCTION WITH TAPE & REEL PACKAGING
- CONTACT PLATING OPTION**
- 2** = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER
- 3** = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

NOTES:

1) MATERIAL:

HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER

2) ROHS COMPLIANT



DO NOT SCALE DRAWING

RECOMMENDED PCB LAYOUT

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

APPROVALS		DATE	Amphenol High Speed Interconnects	
DRAWN	K. LIU	JUN05/12	TITLE	
DESIGNED	C. MICHLIK	JUN05/12		
CHECKED	ZLJ	JUN05/12		
MATERIAL AND FINISH	QA APP'D			
ENG. REL'D	IE APP'D			
CODE IDENT. NO.	03554	JUN05/12	SCALE	NTS
	C. MICHLIK		PROJECT	CFP2
			SHEET	1 OF 1